



# Initial Product/Process Change Notification

Document #: IPCN22951Y3

Issue Date: 11 May 2021

<b>Title of Change:</b>	Update to IPCN22951Y - Update of Qualification Vehicle and timings.
<b>Proposed First Ship date:</b>	30 Jul 2021 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Ivo.Rotthier@onsemi.com">Ivo.Rotthier@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >
<b>Marking of Parts/ Traceability of Change:</b>	By date code
<b>Change Category:</b>	Assembly Change
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer

**Sites Affected:**

ON Semiconductor Sites	External Foundry/Subcon Sites
None	AMKOR, Taiwan T5
	ASEKH, Taiwan (Kaohsiung)

**Description and Purpose:**

This update Notification is issued to update the change description where the qualification vehicle was E7100-102W66-AG is now changed to the hybrid part E7120-102A59-AG containing the E7100-102W66-AG bumped die.

The qualification ready date and first delivery date are updated too.

	Before Change Description	After Change Description
Other Changes: Bump Location	Amkor T5	ASEKH
Other: UBM size	78µm	87µm
Other: Sputter film thickness/material	1KA TiW/ 1.5KA Cu	1KA Ti/ 5KA Cu
Other: UBM thickness/material	2µm/Ni	3µm/Ni

There is no change in bump ball composition.

There is no product marking change as a result of this change.

**Qualification Plan:**QV DEVICE NAME : E7120-102A59-AGRMS : P72893, P74565, I67800, O67799PACKAGE : 59 pad SIP, bumped die are flip chip

Test	Specification	Condition	Interval
TC	JESD22-A104	Ta= --40°C to +85°C	500 cyc
THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
SD	J-STD-002	Ta = 245C	5sec
SBS	JESD22-B117	Cpk > 1.67	
ESD CDM	JS-002-2018	Room Temperature	
PD	Physical Dimension	Per case outline	

Estimated date for qualification completion: 30 Apr 2021

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
E7100-102WC66-BG	E7120-102A59-AG
E7100-102WC66-AG	E7120-102A59-AG